



## P-Channel 1.5-V (G-S) MOSFET

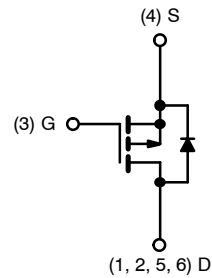
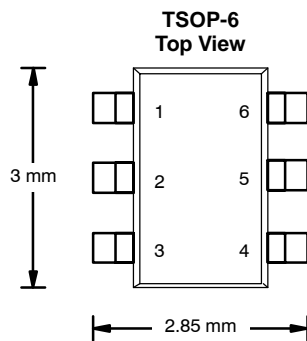
PRODUCT SUMMARY			
$V_{DS}$ (V)	$r_{DS(on)}$ ( $\Omega$ )	$I_D$ (A)	$Q_g$ (Typ)
-8	0.023 @ $V_{GS} = -4.5$ V	-7	28
	0.029 @ $V_{GS} = -2.5$ V	-6.2	
	0.036 @ $V_{GS} = -1.8$ V	-5.2	
	0.048 @ $V_{GS} = -1.5$ V	-5.0	

## FEATURES

- TrenchFET® Power MOSFET: 1.5-V Rated
- Ultra-Low On-Resistance
- 100%  $R_g$  Tested

## APPLICATIONS

- Load Switch for Portable Devices



P-Channel MOSFET

Ordering Information: Si3499DV-T1—E3  
Marking Code: B3xxx

ABSOLUTE MAXIMUM RATINGS ( $T_A = 25^\circ\text{C}$ UNLESS OTHERWISE NOTED)				
Parameter		Symbol	5 secs	Steady State
Drain-Source Voltage		$V_{DS}$	-8	
Gate-Source Voltage		$V_{GS}$	$\pm 5$	
Continuous Drain Current ( $T_J = 150^\circ\text{C}$ ) <sup>a</sup>	$T_A = 25^\circ\text{C}$	$I_D$	-7	-5.3
	$T_A = 85^\circ\text{C}$		-3.6	-3.9
Pulsed Drain Current		$I_{DM}$	-20	
Continuous Diode Current (Diode Conduction) <sup>a</sup>		$I_S$	-1.7	-0.9
Maximum Power Dissipation <sup>a</sup>	$T_A = 25^\circ\text{C}$	$P_D$	2.0	1.1
	$T_A = 85^\circ\text{C}$		1.0	0.6
Operating Junction and Storage Temperature Range		$T_J, T_{stg}$	-55 to 150	

## THERMAL RESISTANCE RATINGS

Parameter		Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient <sup>a</sup>	$t \leq 5$ sec	$R_{thJA}$	45	62.5	$^\circ\text{C/W}$
	Steady State		90	110	
Maximum Junction-to-Foot (Drain)	Steady State	$R_{thJF}$	25	30	

## Notes

a. Surface Mounted on 1" x 1" FR4 Board.

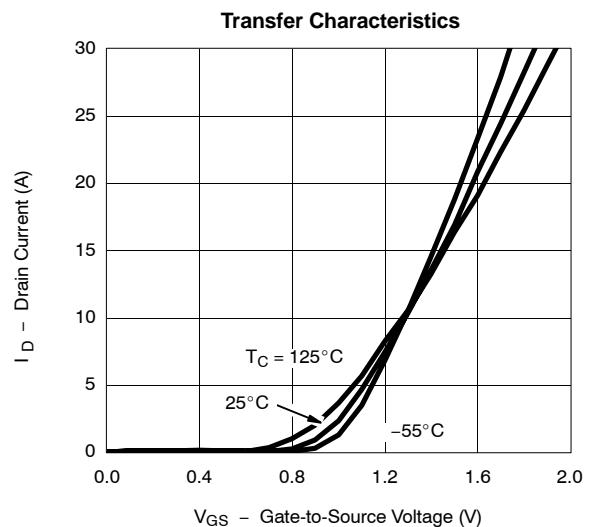
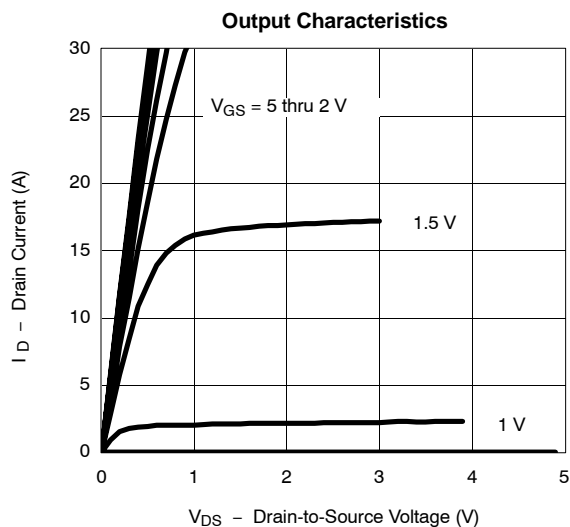
**SPECIFICATIONS ( $T_J = 25^\circ\text{C}$  UNLESS OTHERWISE NOTED)**

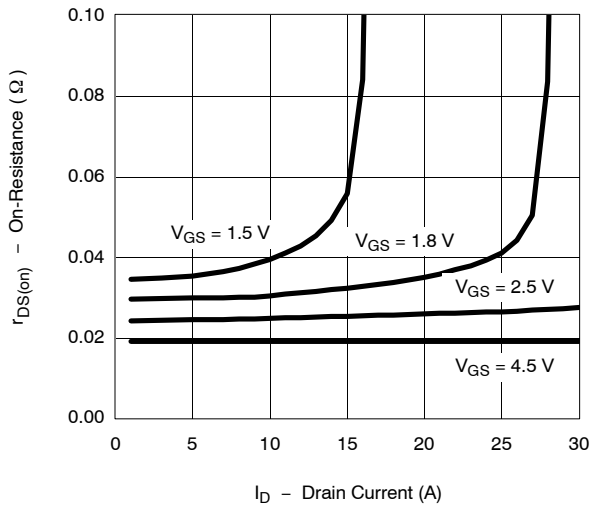
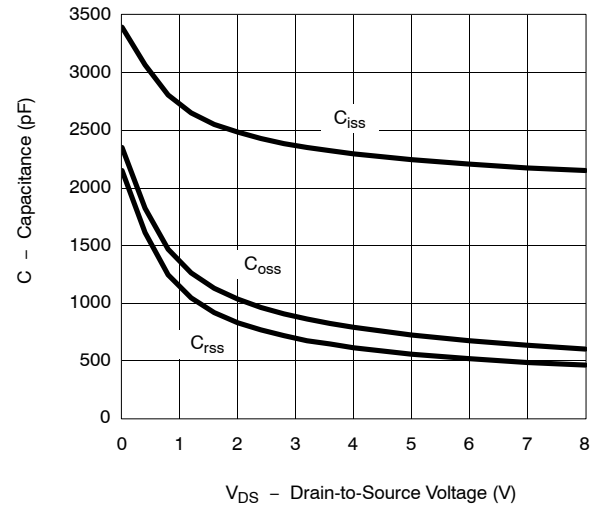
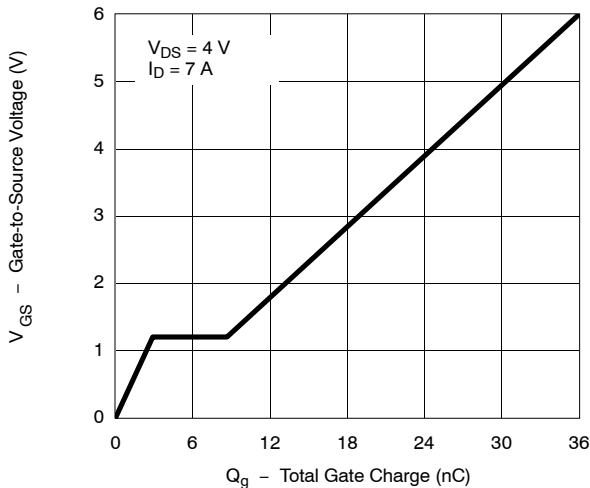
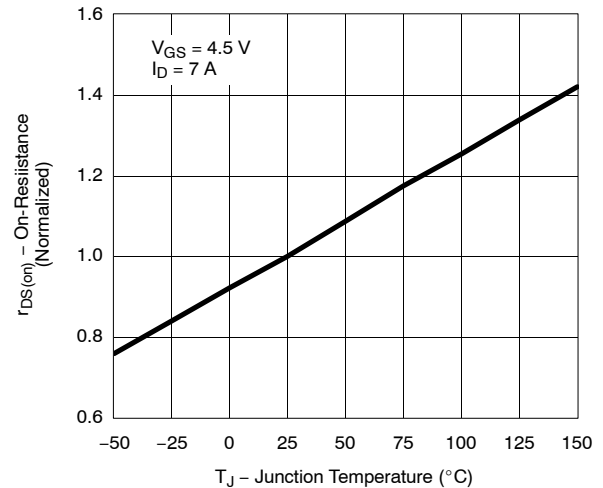
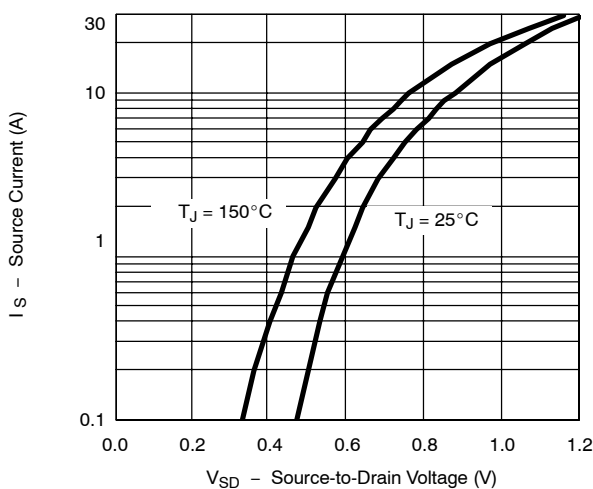
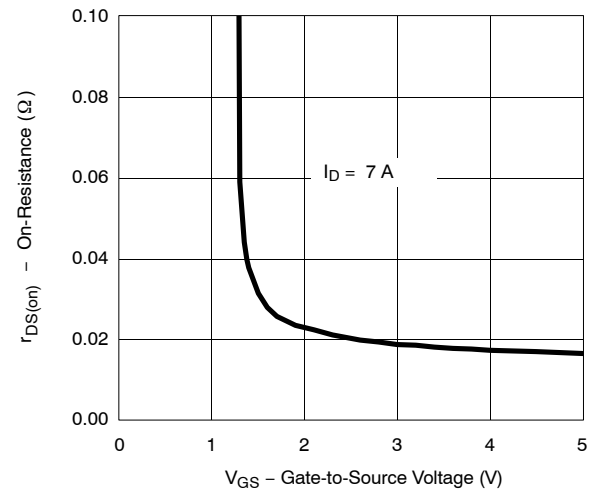
Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
<b>Static</b>						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = -250\ \mu\text{A}$	-0.35		-0.75	V
Gate-Body Leakage	$I_{GSS}$	$V_{DS} = 0\ \text{V}, V_{GS} = \pm 5\ \text{V}$			$\pm 100$	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = -8\ \text{V}, V_{GS} = 0\ \text{V}$			-1	$\mu\text{A}$
		$V_{DS} = -8\ \text{V}, V_{GS} = 0\ \text{V}, T_J = 85^\circ\text{C}$			-10	
On-State Drain Current <sup>a</sup>	$I_{D(on)}$	$V_{DS} = -5\ \text{V}, V_{GS} = -4.5\ \text{V}$	-20			A
Drain-Source On-State Resistance <sup>a</sup>	$r_{DS(on)}$	$V_{GS} = -4.5\ \text{V}, I_D = -7\ \text{A}$		0.019	0.023	$\Omega$
		$V_{GS} = -2.5\ \text{V}, I_D = -6.2\ \text{A}$		0.024	0.029	
		$V_{GS} = -1.8\ \text{V}, I_D = -5.2\ \text{A}$		0.028	0.036	
		$V_{GS} = -1.5\ \text{V}, I_D = -3\ \text{A}$		0.035	0.048	
Forward Transconductance <sup>a</sup>	$g_{fs}$	$V_{DS} = -5\ \text{V}, I_D = -7\ \text{A}$		28		S
Diode Forward Voltage <sup>a</sup>	$V_{SD}$	$I_S = -1.7\ \text{A}, V_{GS} = 0\ \text{V}$		-0.63	-1.1	V
<b>Dynamic<sup>b</sup></b>						
Total Gate Charge	$Q_g$	$V_{DS} = -4\ \text{V}, V_{GS} = -4.5\ \text{V}, I_D = -7\ \text{A}$		28	42	nC
Gate-Source Charge	$Q_{gs}$			2.9		
Gate-Drain Charge	$Q_{gd}$			5.8		
Gate Resistance	$R_g$		4	8.5	13	$\Omega$
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = -4\ \text{V}, R_L = 4\ \Omega$ $I_D \cong -1\ \text{A}, V_{GEN} = -4.5\ \text{V}, R_g = 6\ \Omega$		27	40	ns
Rise Time	$t_r$			65	100	
Turn-Off Delay Time	$t_{d(off)}$			210	315	
Fall Time	$t_f$			110	165	
Source-Drain Reverse Recovery Time	$t_{rr}$	$I_F = -1.7\ \text{A}, di/dt = 100\ \text{A}/\mu\text{s}$		40	70	

## Notes

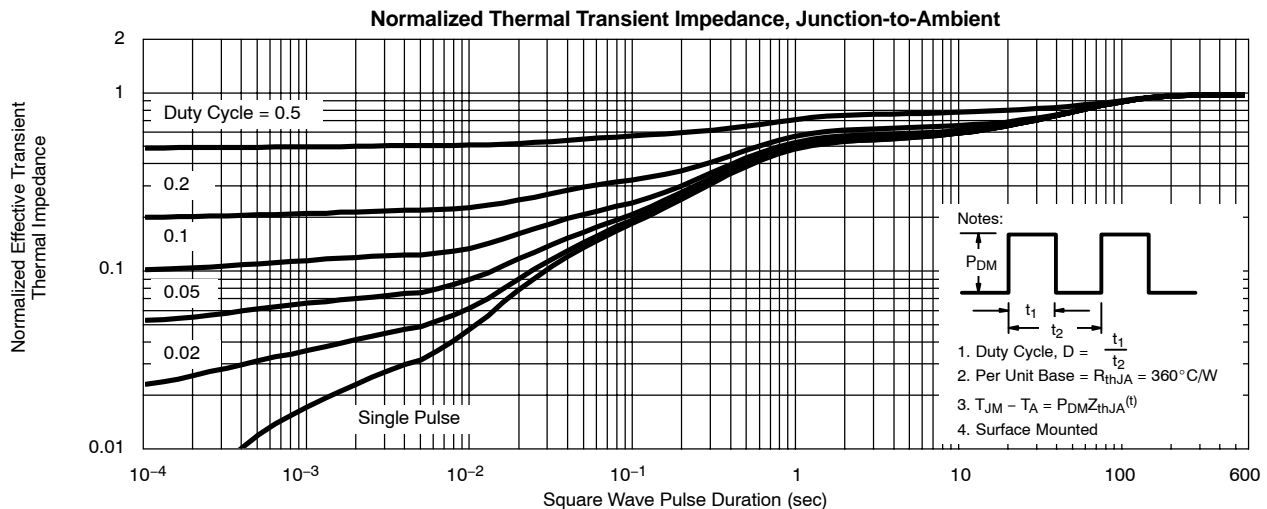
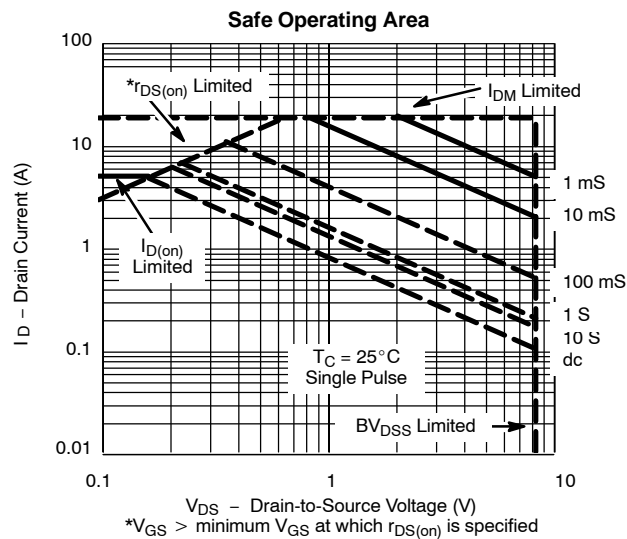
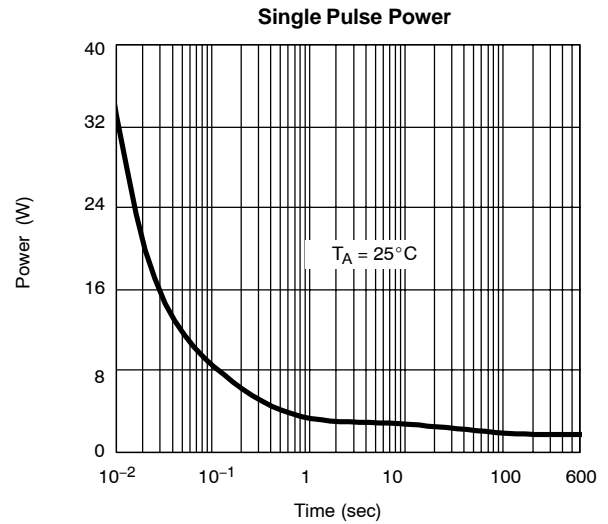
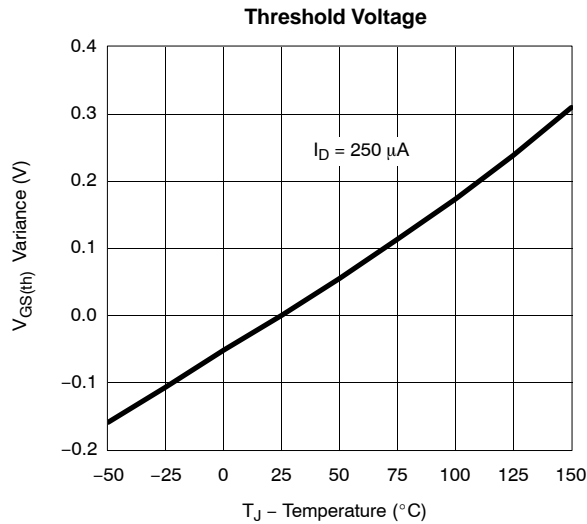
- a. Pulse test; pulse width  $\leq 300\ \mu\text{s}$ , duty cycle  $\leq 2\%$ .  
b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

**TYPICAL CHARACTERISTICS ( $25^\circ\text{C}$  UNLESS NOTED)**

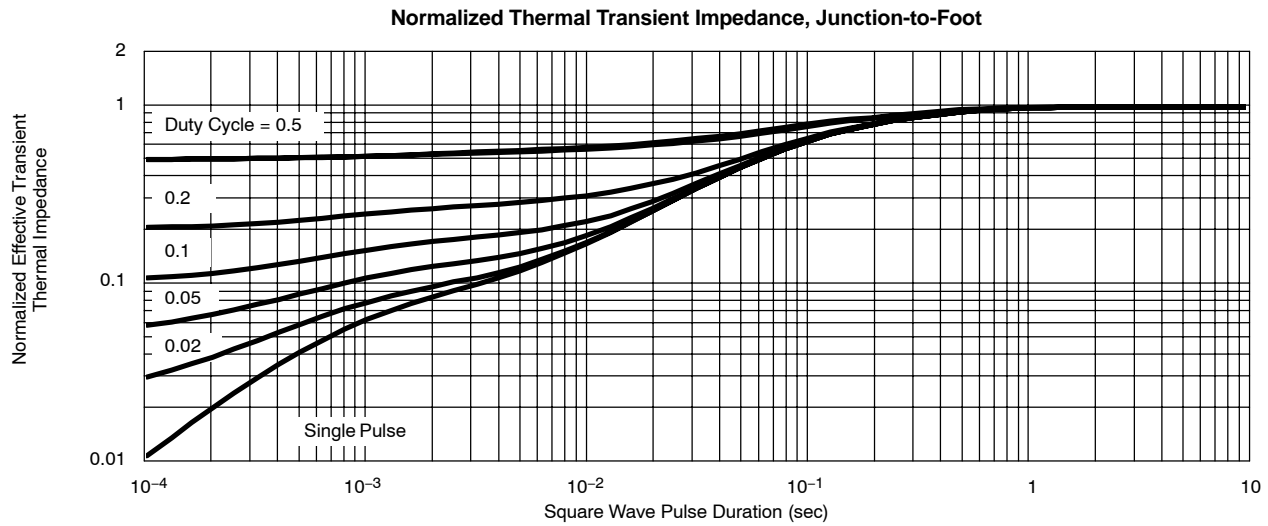
**TYPICAL CHARACTERISTICS (25 °C UNLESS NOTED)****On-Resistance vs. Drain Current****Capacitance****Gate Charge****On-Resistance vs. Junction Temperature****Source-Drain Diode Forward Voltage****On-Resistance vs. Gate-to-Source Voltage**

## TYPICAL CHARACTERISTICS (25 °C UNLESS NOTED)





**TYPICAL CHARACTERISTICS (25 °C UNLESS NOTED)**



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